

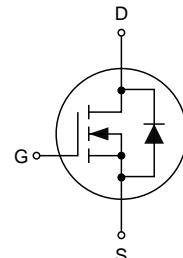
N-Channel Enhancement Mode MOSFET

1. Product Information

Features

- Advanced Trench Technology
- Excellent $R_{DS(ON)}$, Low gate charge

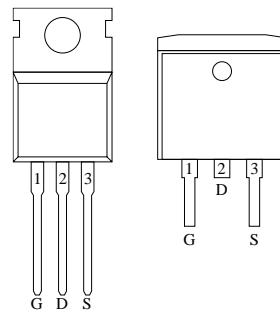
Schematic diagram



Applications

- Brushless motor
- Load switch
- Uninterruptible power supply

Pin Assignment



TO-220 TO-263

Quick reference

- $V_{DS} = 40V$
 $I_D = 120A$
 $R_{DS(ON)} \leq 4.0m\Omega @ V_{GS} = 10V$ (Type: $3.0m\Omega$)

Package Marking and Ordering Information

Product Name	Package	Marking	Reel Size	Tape width	Quantity
KJ120N04C	TO-220	120N04 YWWXXX: Date Code	-	-	1000
KJ120N04D	TO-263		-	-	800

2. Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Values	Unit
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current, $T_C=25^\circ C$ ^{1,6}	120	A
	Continuous Drain Current, $T_C=100^\circ C$ ^{1,6}	98	A
I_{DM}	Pulsed Drain Current ²	600	A
E_{AS}	Single pulse avalanche energy ³	272	mJ
I_{AS}	Single pulse avalanche current	33	A
P_D	Power Dissipation ⁴	180	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55~150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	50	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.7	$^\circ C/W$

3. Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0 \text{ V}, I_{\text{D}}=250 \mu\text{A}$	40	-	-	V
$V_{\text{GS(th)}}$	Gate-Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250 \mu\text{A}$	2.5	2.8	4.0	V
I_{GSS}	Gate to Body Leakage Current	$V_{\text{DS}}=0 \text{ V}, V_{\text{GS}}=\pm 20 \text{ V}$	-	-	± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=40 \text{ V}, V_{\text{GS}}=0 \text{ V}$	-	-	1	μA
$R_{\text{DS(ON)}}$	Drain-Source On-Resistance ³	$V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=30 \text{ A}$	-	3.0	4.0	$\text{m}\Omega$
C_{iss}	Input Capacitance	$V_{\text{DS}}=20 \text{ V}, V_{\text{GS}}=0 \text{ V}, f=1.0 \text{ MHz}$	-	4900	-	pF
C_{oss}	Output Capacitance		-	528	-	
C_{rss}	Reverse Transfer Capacitance		-	317	-	
Q_g	Total Gate Charge	$V_{\text{DS}}=20 \text{ V}, V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=30 \text{ A}$	-	80	-	nC
Q_{gs}	Gate-Source Charge		-	17	-	
Q_{gd}	Gate-Drain Charge		-	21	-	
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=20 \text{ V}, V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=30 \text{ A}, R_{\text{L}}=1 \Omega, R_{\text{GEN}}=3 \Omega$	-	21	-	ns
t_r	Turn-on Rise Time		-	32	-	
$t_{\text{d(off)}}$	Turn-off Delay Time		-	71	-	
t_f	Turn-off Fall Time		-	40	-	
V_{SD}	Diode Forward Voltage	$V_{\text{GS}}=0 \text{ V}, I_{\text{s}}=30 \text{ A}$	-	-	1.2	V
I_{s}	Diode Forward Current		-	-	150	A
I_{SM}	Diode Pulse Current		-	-	600	A
t_{rr}	Reverse Recovery Time	$V_{\text{GS}}=10 \text{ V}, I_{\text{s}}=20 \text{ A}, dI/dt=100 \text{ A}/\mu\text{s}$	-	27	-	ns
Q_{rr}	Reverse Recovery Charge		-	46	-	

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. The E_{AS} data shows Max. rating. The test condition is $T_J=25^\circ\text{C}$, $V_{\text{DD}}=20 \text{ V}$, $V_{\text{G}}=10 \text{ V}$, $L=0.5 \text{ mH}$, $R_g=25 \Omega$, $I_{\text{AS}}=33 \text{ A}$
3. The data tested by pulsed, pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as I_{D} and I_{DM} , in real applications, should be limited by total power dissipation.
6. Package limitation current is 180 A

4. Typical Characteristics

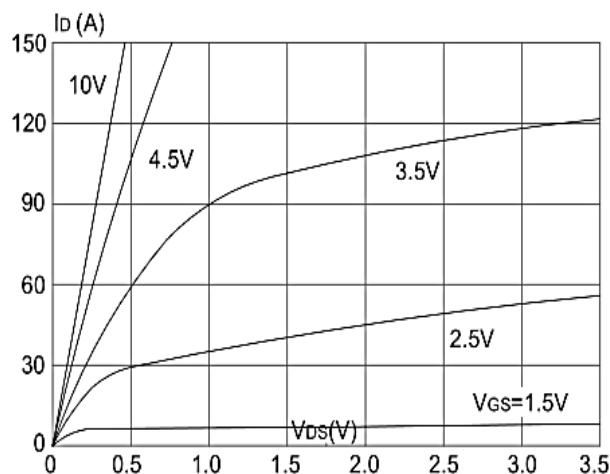


Figure 1: Output Characteristics

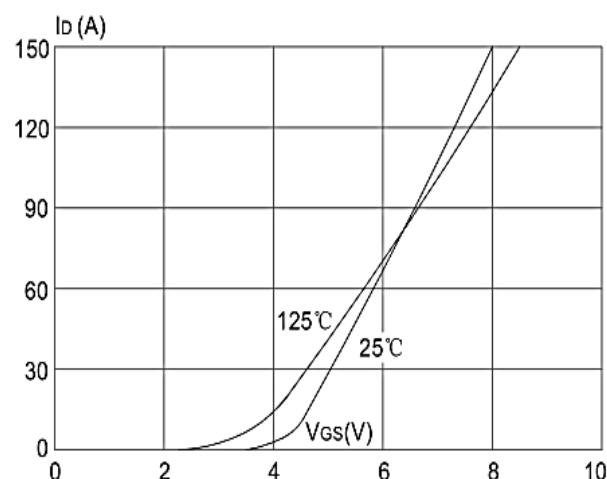


Figure 2: Typical Transfer Characteristics

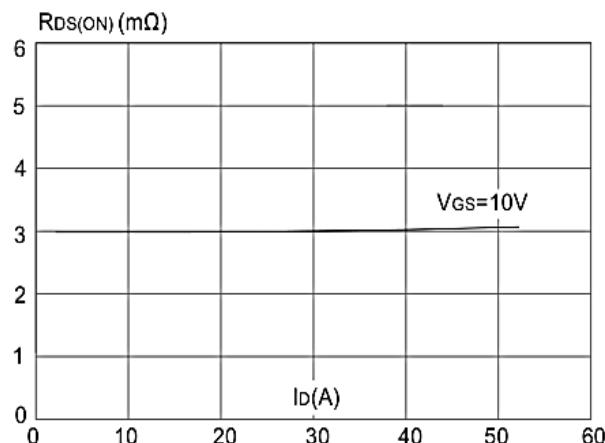


Figure 3: On-resistance vs. Drain Current

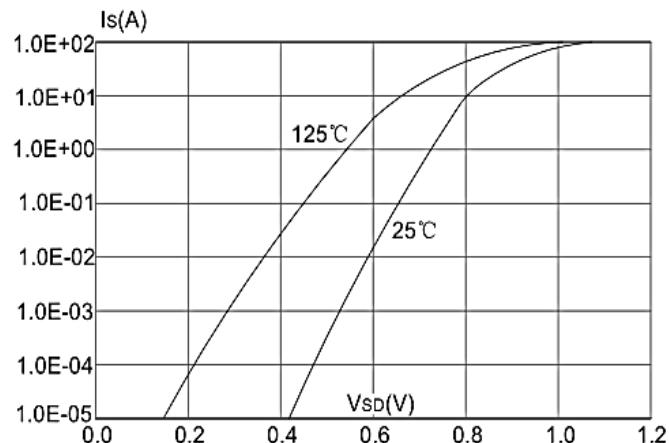


Figure 4: Body Diode Characteristics

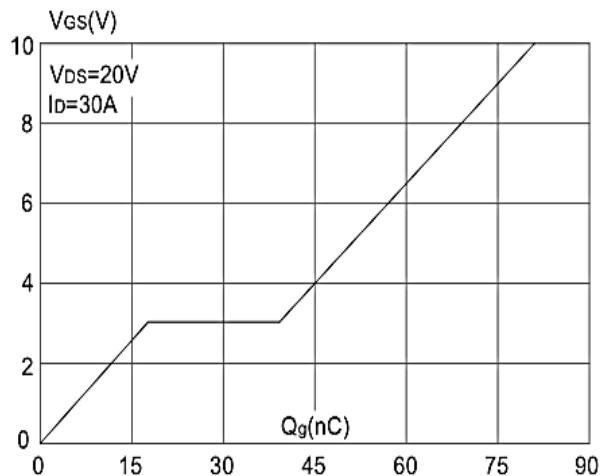


Figure 5: Gate Charge Characteristics

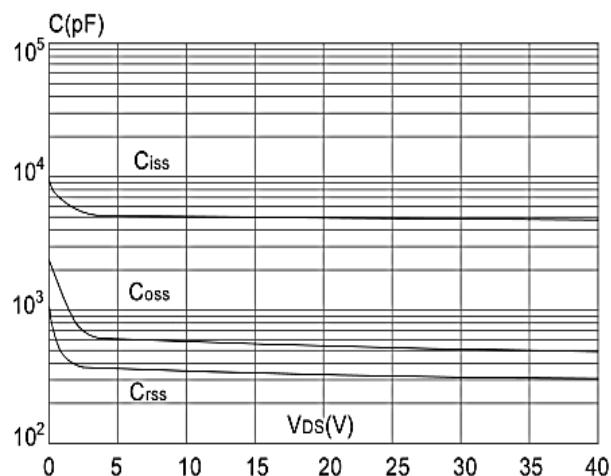


Figure 6: Capacitance Characteristics

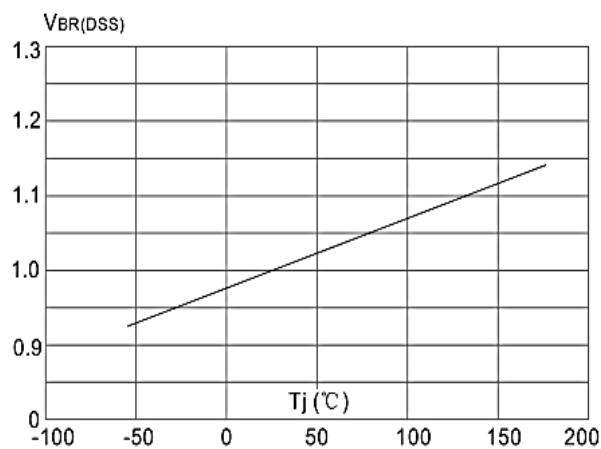


Figure 7: Normalized Breakdown Voltage vs Junction Temperature

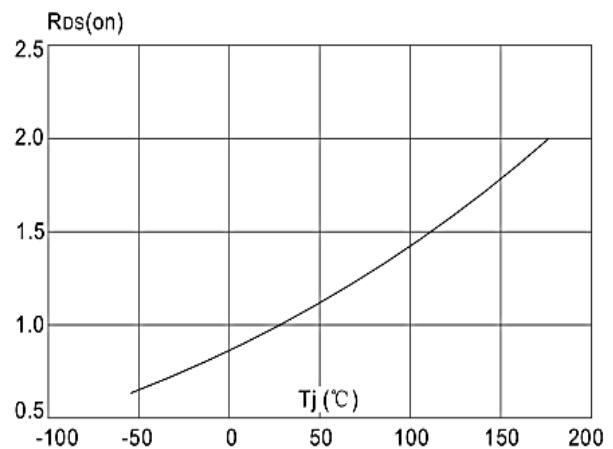


Figure 8: Normalized on Resistance vs. Junction Temperature

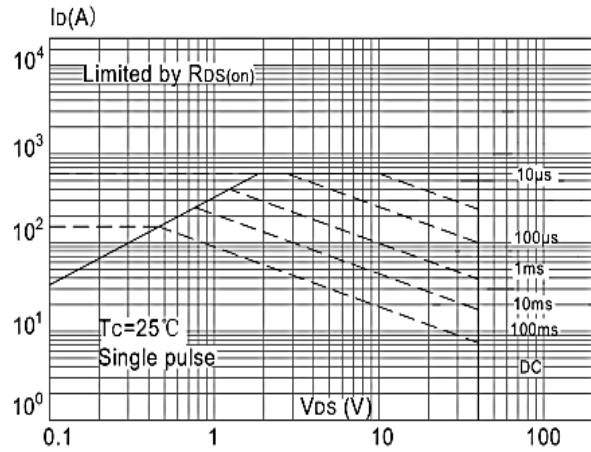


Figure 9: Maximum Safe Operating Area

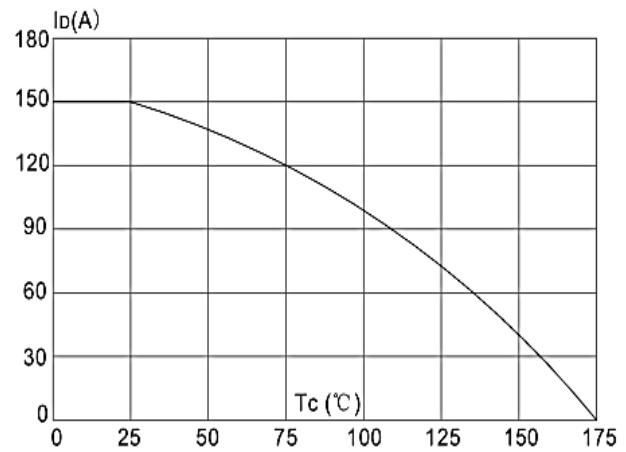


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

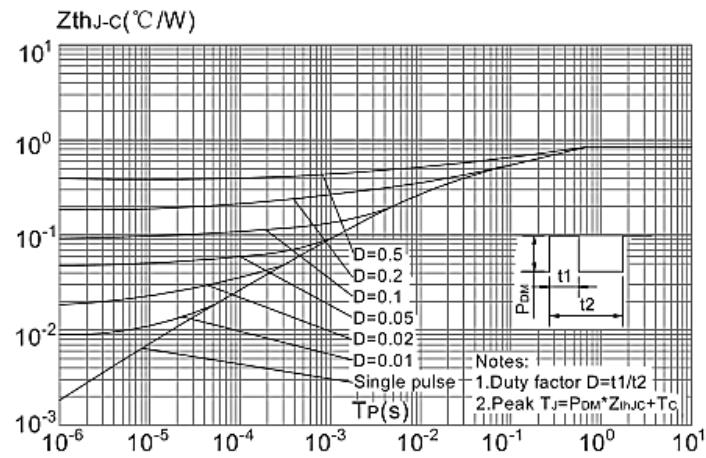
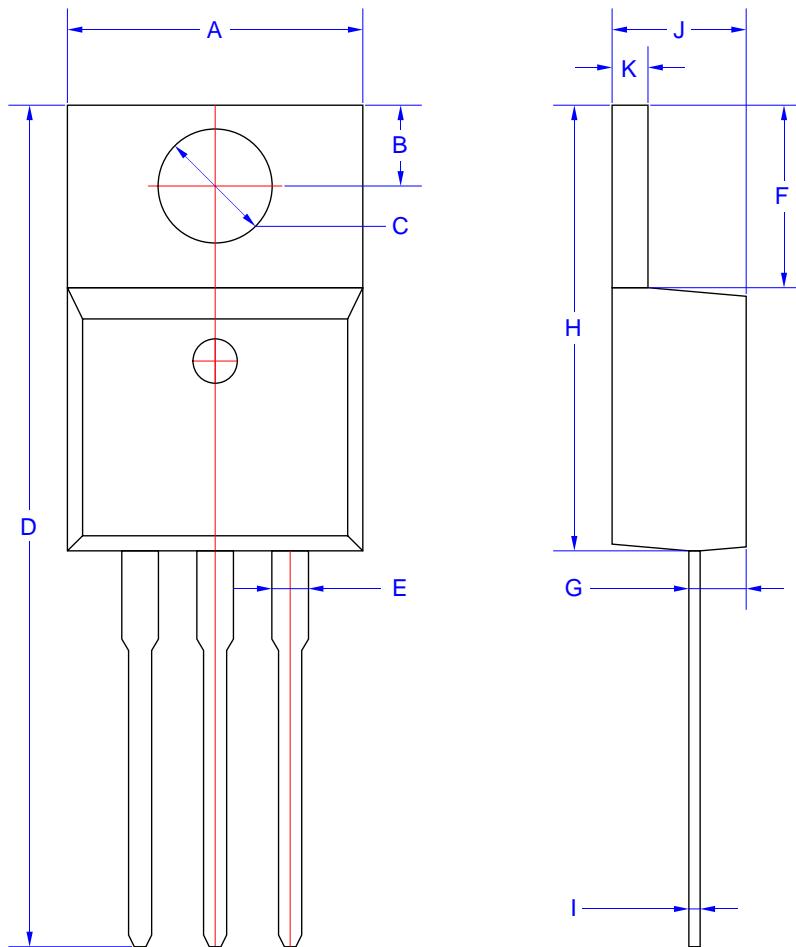


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

5. Package Mechanical Data

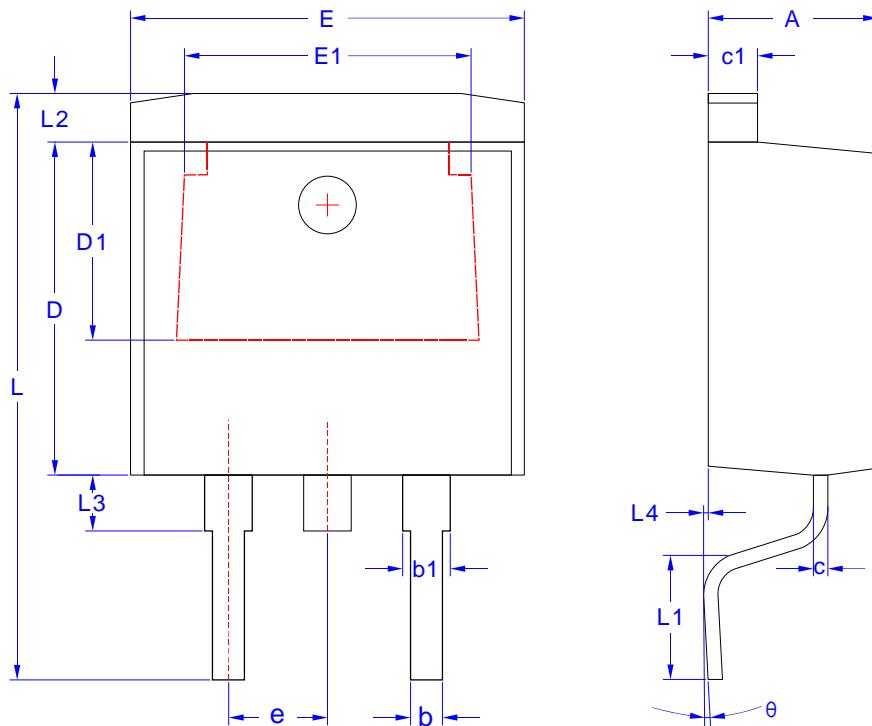
TO-220 Package



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	10.0	10.4
B	2.5	3.0
C	3.5	4.0
D	28.0	30.0
E	1.1	1.5
F	6.2	6.6
G	2.9	3.3
H	15.0	16.0
I	0.35	0.45
J	4.3	4.7
K	1.2	1.4

5. Package Mechanical Data

TO-263 Package



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	4.40	4.80
b	0.76	1.00
b1	1.17	1.47
c	0.36	0.50
c1	1.25	1.45
D	8.60	9.00
D1	5.10 REF	
E	9.80	10.40
E1	7.40 REF	
e	2.54 REF	
L	14.6	15.8
L1	2.29	2.79
L2	1.27 REF	
L3	1.50 REF	
L4	0.00	0.25
theta	$0^\circ \pm 3^\circ$	